

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3979676

|   |                                  |
|---|----------------------------------|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                   |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                       |
| <b>CONVEYING PARTY DATA</b>   |                                  |
| <b>Name</b>   | <b>Execution Date</b>            |
| HIROYUKI TEMMEI   | 06/05/2016                       |
| MINA AMO  | 06/02/2016                       |
| NOBUTAKE TSUYUNO  | 05/31/2016                       |
| EIICHI IDE  | 06/01/2016                       |
| TAKESHI TOKUYAMA  | 06/09/2016                       |
| TOSHIYA SATOH   | 05/31/2016                       |
| TOSHIKI ISHII   | 06/02/2016                       |
| KAZUAKI NAOE  | 06/13/2016                       |
| <b>RECEIVING PARTY DATA</b>   |                                  |
| <b>Name:</b>  | HITACHI AUTOMOTIVE SYSTEMS, LTD. |
| <b>Street Address:</b>  | 2520, TAKABA                     |
| <b>City:</b>  | HITACHINAKA-SHI, IBARAKI         |
| <b>State/Country:</b>   | JAPAN                            |
| <b>PROPERTY NUMBERS Total: 1</b>  |                                  |
| <b>Property Type</b>  | <b>Number</b>                    |
| <b>Application Number:</b>  | 15114431                         |
| <b>CORRESPONDENCE DATA</b>  |                                  |
| <b>Fax Number:</b>  | (202)628-8844                    |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |                                  |
| <b>Phone:</b>   | 202-624-2500                     |
| <b>Email:</b>   | eoconnell@crowell.com            |
| <b>Correspondent Name:</b>  | CROWELL & MORING LLP             |
| <b>Address Line 1:</b>  | P.O. BOX 14300                   |
| <b>Address Line 4:</b>  | WASHINGTON, D.C. 20044-4300      |
| <b>ATTORNEY DOCKET NUMBER:</b>  | 105920.69327US                   |
| <b>NAME OF SUBMITTER:</b>   | CAMERON W. BEDDARD               |
| <b>SIGNATURE:</b>   | /Cameron W. Beddard/             |
| <b>DATE SIGNED:</b>   | 07/27/2016                       |

**Total Attachments: 8**

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# ASSIGNMENT

( 譲渡証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI AUTOMOTIVE SYSTEMS, LTD., a corporation organized under the laws of Japan, located at 2520, Takaba, Hitachinaka-shi, Ibaraki, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## WATERPROOF ELECTRONIC DEVICE AND MANUFACTURING METHOD THEREOF

invented by me (if only one is named below ) or us (if plural inventors are named below ) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI AUTOMOTIVE SYSTEMS, LTD.

Signed on the date(s) indicated aside signatures:

| INVENTOR(S)<br>(発明者フルネームサイン)                     | Date Signed<br>(署名日) |
|--|----------------------|
| 1) <u>Hiroyuki TEMMEI</u> <u>Hiroyuki Tenmei</u> | <u>5 June, 2016</u>  |
| 2) <u>Mina AMO</u>                               |                      |
| 3) <u>Nobutake TSUYUNO</u>                       |                      |
| 4) <u>Eiichi IDE</u>                             |                      |
| 5) <u>Takeshi TOKUYAMA</u>                       |                      |
| 6) <u>Toshiya SATOH</u>                          |                      |
| 7) <u>Toshiaki ISHII</u>                         |                      |
| 8) <u>Kazuaki NAOE</u>                           |                      |
| 9) _____   |                      |

# ASSIGNMENT (譲渡証)

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INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) Hiroyuki TEMMEI

2) Mina AMO

3) Nobutake TSUYUNO

4) Eiichi IDE

5) Takeshi TOKUYAMA

6) Toshiya SATOH

7) Toshiaki ISHII

8) Kazuaki NAOE

9)

June 2, 2016

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|--|----------------------|
| 1) <u>Hiroyuki TEMMEI</u>                          |                      |
| 2) <u>Mina AMO</u>                                 |                      |
| 3) <u>Nobutake TSUYUNO</u> <i>Nobutake Tsuyuno</i> | <u>5 / 31 / 2016</u> |
| 4) <u>Eiichi IDE</u>                               |                      |
| 5) <u>Takeshi TOKUYAMA</u>                         |                      |
| 6) <u>Toshiya SATOH</u>                            |                      |
| 7) <u>Toshiki ISHII</u>                            |                      |
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| 9) _____   |                      |

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Date Signed  
(署名日)

- |                     |           |
|---------------------|-----------|
| 1) Hiroyuki TEMMEI  |           |
| 2) Mina AMO         |           |
| 3) Nobutake TSUYUNO |           |
| 4) Eiichi IDE       | 11/6/2016 |
| 5) Takeshi TOKUYAMA |           |
| 6) Toshiya SATOH    |           |
| 7) Toshiaki ISHII   |           |
| 8) Kazuaki NAOE     |           |
| 9)                  |           |

REEL: 039266 FRAME: 0337

## ASSIGNMENT ( 譲渡証 )

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INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) Hiroyuki TEMMEI

---

2) Mina AMO

3) Nobutake TSUYUNO

#### 4) Ellich IDE

5) Takeshi TOKUYAMA *Takeshi Tokuyama*

Takeshi Tokuyama

Jun 19 / 2016

6) Toshiya SATOH

7) Toshiaki ISHII

8) Kazuaki NAOE

g)

## PATENT

REEL: 039266 FRAME: 0338

**ASSIGNMENT**  
( 譲渡証 )

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| 3) <u>Nobutake TSUYUNO</u>                   | _____                |
| 4) <u>Eiichi IDE</u>                         | _____                |
| 5) <u>Takeshi TOKUYAMA</u>                   | _____                |
| 6) <u>Toshiya SATOH</u> <i>Toshiya Satoh</i> | <i>31 May 2016</i>   |
| 7) <u>Toshiaki ISHII</u>                     | _____                |
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| 9) _____                                     | _____                |



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5) Takeshi TOKUYAMA

6) Toshiya SATOH

7) Toshiaki ISHII / 05h1a KL / 9h1L

8) Kazuaki NAOE

9)

**PATENT**  
**REEL: 039266 FRAME: 0340**

( 讓 渡 証 )

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8) Kazuaki NAOE Kazuaki Naoe

9) \_\_\_\_\_

6/13/2016